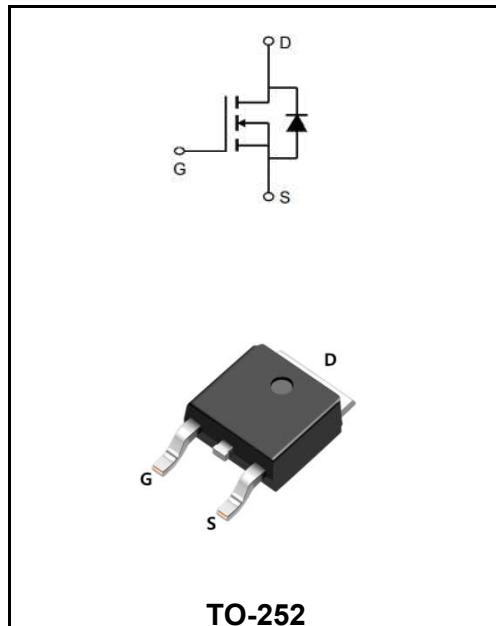


20V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	50A
V_{DSS}	20V
$R_{DS(on)-typ}(@V_{GS}=4.5V)$	< 10.5mΩ (Type: 8.5 mΩ)


Application

- Battery protection
- Load switch
- Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW2222AD	TO-252	YFW 2222AD XXXXX	2500PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

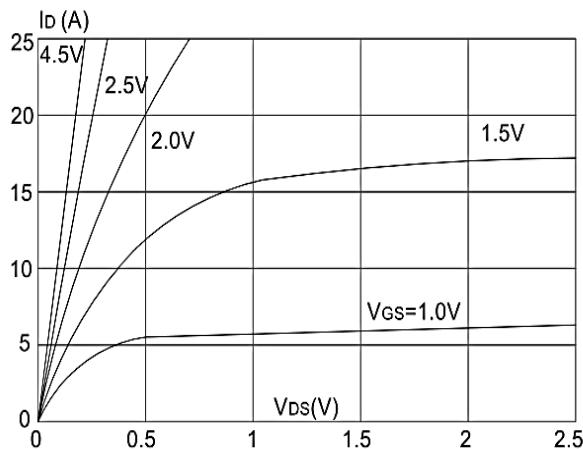
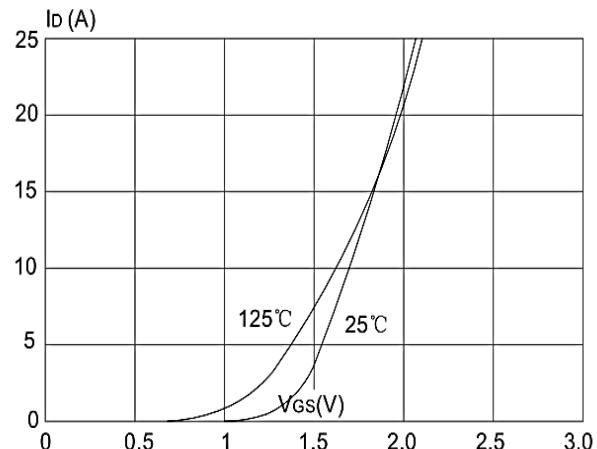
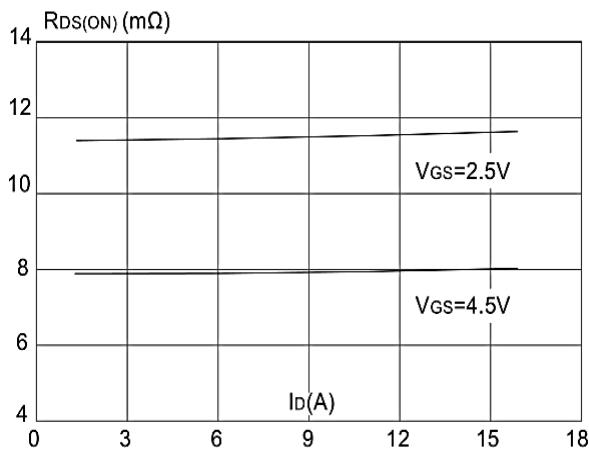
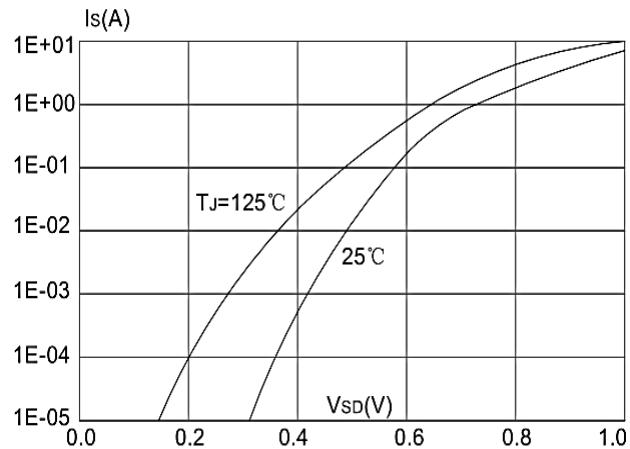
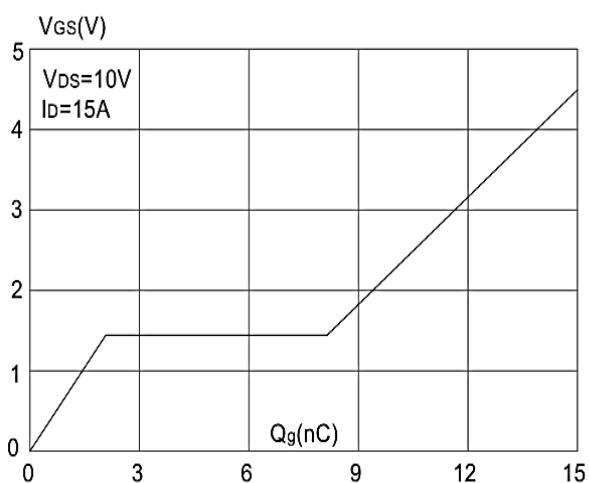
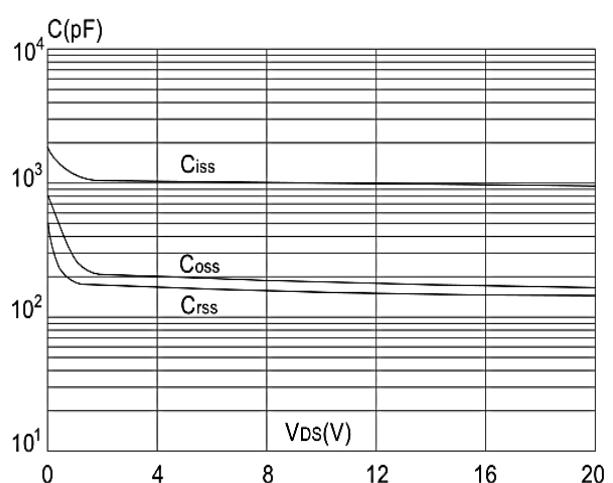
Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	20	V
Gate - Source Voltage	V_{GS}	± 12	V
Continuous Drain Current, $V_{GS} @ 4.5V @ T_A=25^\circ\text{C}$	I_D	50	A
Continuous Drain Current, $V_{GS} @ 4.5V @ T_A=70^\circ\text{C}$	I_D	20	A
Pulsed Drain Current ^{note1}	I_{DM}	120	A
Single Pulse Avalanche Energy ^{note2}	E_{AS}	23	mJ
Power Dissipation	P_D	20	W
Thermal Resistance Junction to Case	$R_{\theta JC}$	7.5	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	V(BR)DSS	20	24	-	V
Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	I _{DSS}	-	-	1.0	μA
Gate - Body Leakage Current	V _{GS} =±12V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	V _{GS(th)}	0.5	0.75	1.2	V
Static Drain-Source on-Resistance note3	V _{GS} =4.5V, I _D =15A	R _{DS(ON)}	-	8.5	10.5	mΩ
	V _{GS} =2.5V, I _D =10A		-	11.7	17.5	
Input Capacitance	V _{DS} =10V V _{GS} =0V f=1.0MHz	C _{iss}	-	1000	1500	pF
Output Capacitance		C _{oss}	-	182	-	
Reverse Transfer Capacitance		C _{rss}	-	164	-	
Total Gate Charge	V _{DS} =10V I _D =15A V _{GS} =4.5V	Q _g	-	15	-	nC
Gate-Source Charge		Q _{gs}	-	2	-	
Gate-Drain("Miller") Charge		Q _{gd}	-	5.2	-	
Turn-on delay time	V _{DS} =10V I _D = 15A R _{GEN} = 3Ω V _{GS} =4.5V	t _{D(on)}	-	9	-	ns
Turn-on Rise Time		T _r	-	25	-	
Turn-Off Delay Time		t _{d(OFF)}	-	37	-	
Turn-Off Fall Time		t _f	-	14	-	
Maximum Continuous Drain to Source Diode Forward Current	I _S	-	-	-	30	A
Maximum Pulsed Drain to Source Diode Forward Current	I _{SM}	-	-	-	120	A
Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	V _{SD}	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. The test condition is, VDD=10V, VG=4.5V, L=0.5mH, RG=25Ω, IAS=9.6A
3. The data tested by pulsed Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%
4. The power dissipation is limited by 150°C junction temperature

Ratings and Characteristic Curves
Typical Characteristics

Figure 1: Output Characteristics

Figure 2: Typical Transfer Characteristics

Figure 3: On-resistance vs. Drain Current

Figure 4: Body Diode Characteristics

Figure 5: Gate Charge Characteristics

Figure 6: Capacitance Characteristics

Ratings and Characteristic Curves

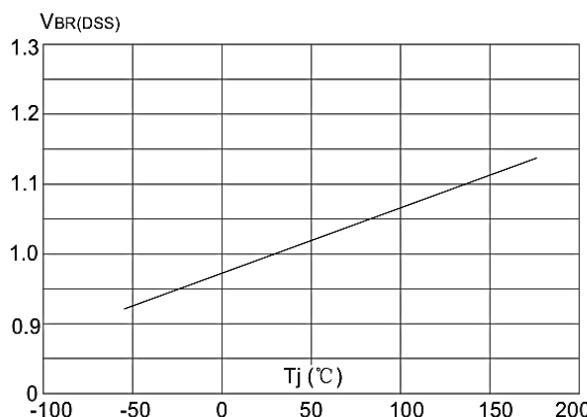


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

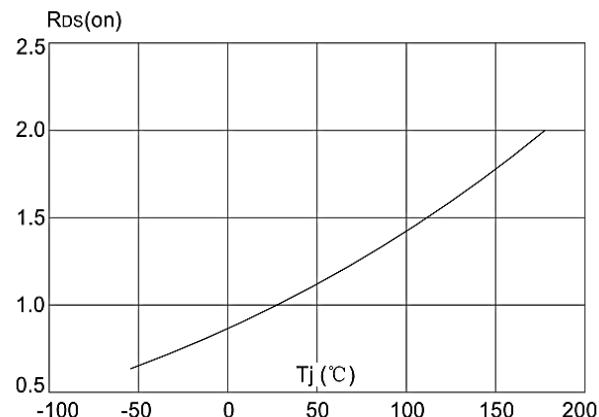


Figure 8: Normalized on Resistance vs. Junction Temperature

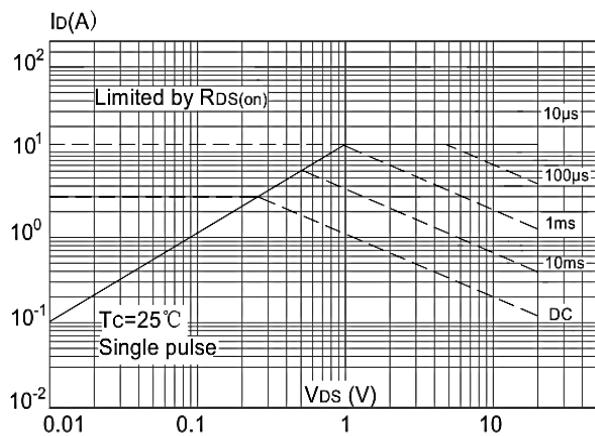


Figure 9: Maximum Safe Operating Area Current vs. Temperature

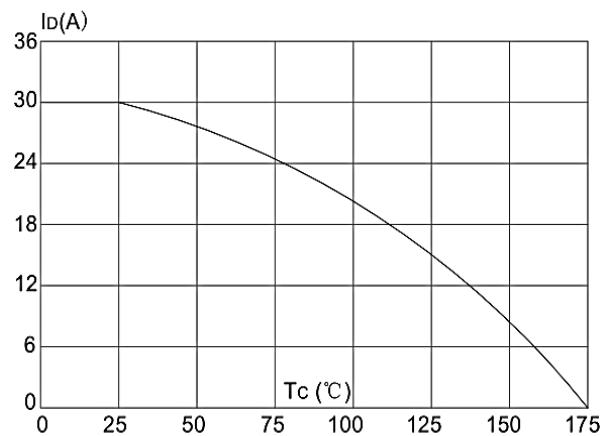


Figure 10: Maximum Continuous Drain Current vs. Case

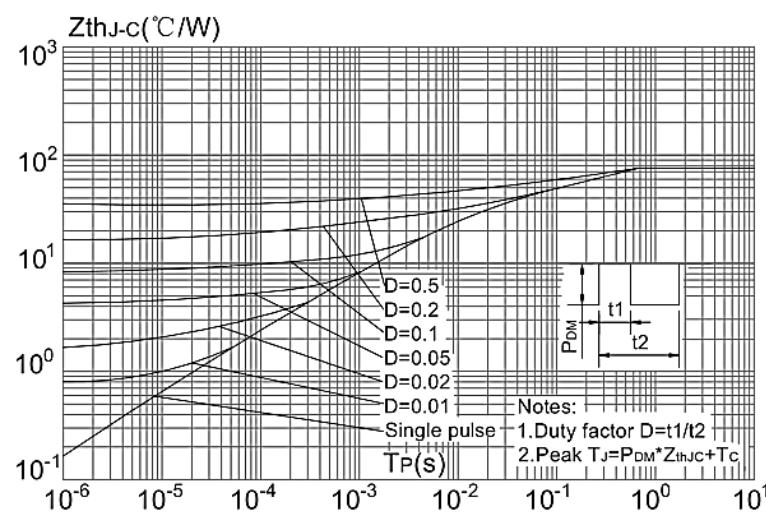
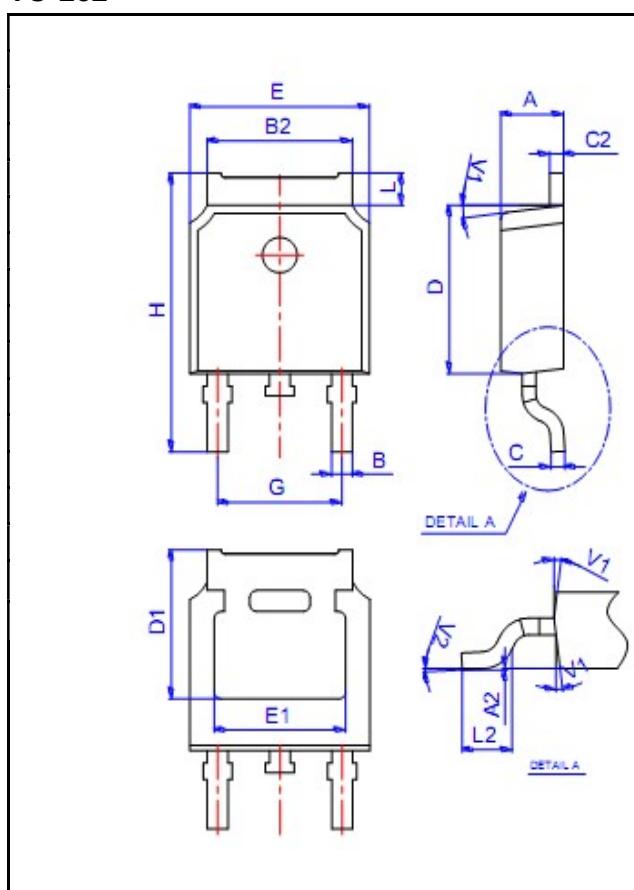


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

Package Outline Dimensions Millimeters

TO-252



Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter